Computing Evolution: Technology and Markets

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Presenting material prepared by Bernd Panzer-Steindel / CERN



Outline

- Semiconductor market
- Device market
- Processors
- Hard Disk
- Solid-State Disks
- Memory
- Tapes
- Server
- Summary
- References



General Market,

Few companies dominating the markets

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Server CPUs	Intel (99%)	
FPGA	Xilinx (49%), Intel (38%)	Source: WSTS
GPU	Intel (72%), Nvidia (14%), AMD (14%))
Hard disks	Western Digital (44%), Seagate (40%), Toshiba
Tape drives	HP, IBM, Oracle	
Tape media	Fujifilm, Sony	
NAND	Samsung (45%), Toshiba, Western Di	igital, Intel
DRAM	Samsung (47%), Hynix, Micron/Intel	

Forecast for 2016: +1.5%

Total: ~340 B\$/y

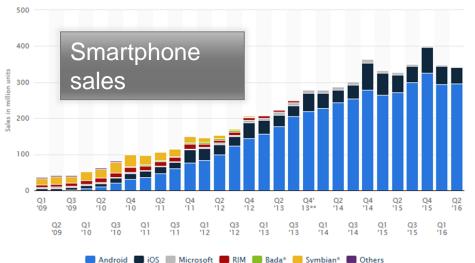
Started negative in first part of 2016 and recovered at the end (e.g. memory price increases)

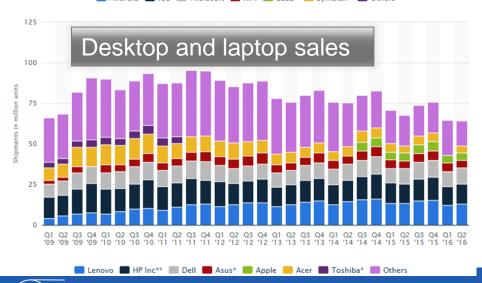


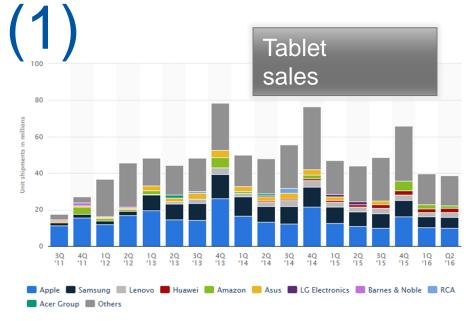
23-Jan-2017 Technology tracking

Year-to-Year Percent Change

Device Markets (1)







Market saturation: minimal or negative growth rates Longer product lifetimes

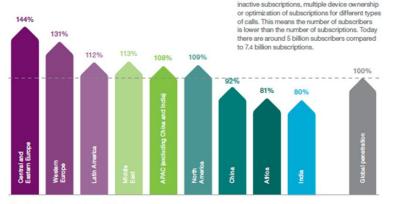
Smartphones	0-2 %
Tablets	-12%
Desktops and laptops	-7%
Servers	-3%



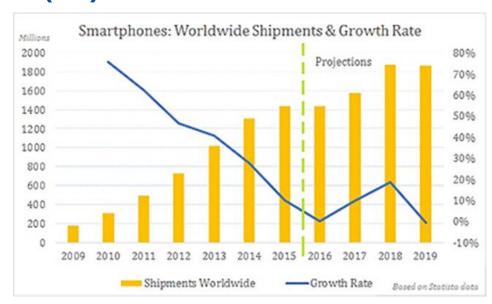
Device Markets (2)

The number of mobile subscriptions exceeds the population in many countries. This is largely due to





Penetration (percent of population)



Saturation:

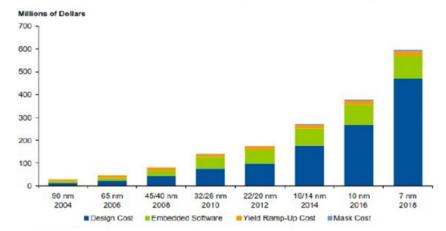
7.3 B phone subscriptions world-wide – more than the population

Replacement bump expected in 2018



Processors (1)

Estimated Cost of Developing Lower Node Chips



Market Realist^Q Source: Gartner

Г.												
Ш	SMIC											
	Hitachi							Source	e: I	BS, Inc. (Los G	ato	os, CA)
	NEC	SMIC										
	Sony	Sony										
	NXP	NXP										
	Infineon	Infineon	Γ.									
	Renesas	Renesas		Renesas								
П	Freescale	Freescale		SMIC	Г							
Ш	TI	TI		TI		SMIC						
П	Fujitsu	Fujitsu		Fujitsu		Fujitsu						
Ш	Panasonic	Panasonic		Panasonic		Panasonic						
	Toshiba	Toshiba		Toshiba	Г	Toshiba		SMIC				
	UMC	UMC		UMC	L	UMC		UMC				
П	IBM	IBM		IBM	Г	IBM		IBM		IBM		
	STM	STM		STM		STM		STM		STM		
	G'Foundries	G'Foundries		G'Foundries		G'Foundries		G'Foundries		G'Foundries		G'Foundries
	TSMC	TSMC		TSMC	L	TSMC		TSMC		TSMC		TSMC
	Samsung	Samsung		Samsung		Samsung		Samsung		Samsung		Samsung
Ш	Intel	Intel	Ц	Intel	Ļ	Intel	L	Intel	Ц	Intel		Intel
	0.13µm	90nm		65nm		40/45nm		28/32nm		20/22 nm		14/16nm
	2001	2003		2005		2007		2009		2012		2015

Figure 4. Dramatic Consolidation of state of the art CMOS Fabs. Source: IBS , Inc. (Los Gatos, CA).

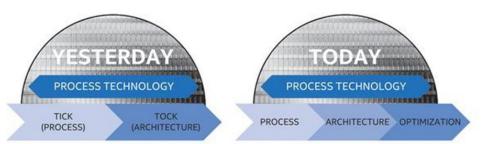
2003 2005 2007 2009 2012 2015 Techno

Non-linear costs for development

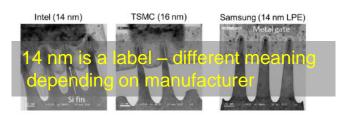
- Only four companies able to fabricate 14 nm chips
- 10 nm Samsung fab costs \$14 B



Processors (2)



Intel moved from 2-year cycle to 3 years or more



Feature	Intel	TSMC	Samsung	
Gate length (nm)	24	33	30	1
Min contacted gate pitch (nm)	70	90	78	Intel transistors
Fin height under gate (nm)	42	37	37	are smaller than
Fin pitch (nm)	43	45	49	TSMC or Samsun
Min metal pitch (nm)	52	70	67	



#TheConFab2016

or Samsung

Incubation Time

Strained Silicon

• 1992-> **2003**

HKMG

• 1996->2007

Raised S/D

• 1993->2009

■ MultiGates

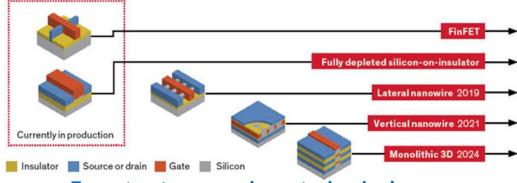
• 1997->2011



~ 12-15 years

Decrease of feature size goes along with new material technologies

R&D → production needs 12-15 years



7nm structures need new technologies: nanowires and non-silicon material

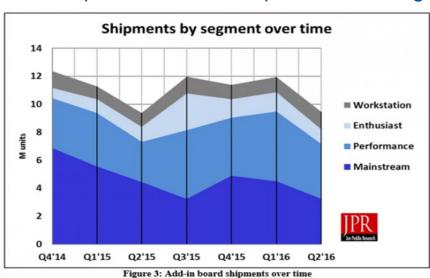


Accelerators: GPU (1)

Embedded market shares (CPU+GPU): Intel 72%, Nvidia 16%, AMD 12%

Discrete GPU cards: Nvidia 77%, AMD 23%

Desktop and notebook shipments declining



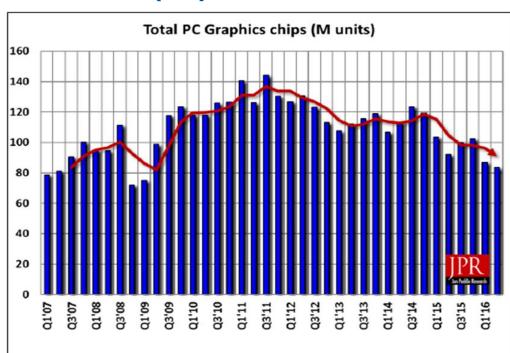


Figure 3: While PC shipments have returned to predictable patterns, graphics shipments have been erratic and defy any seasonal attributes

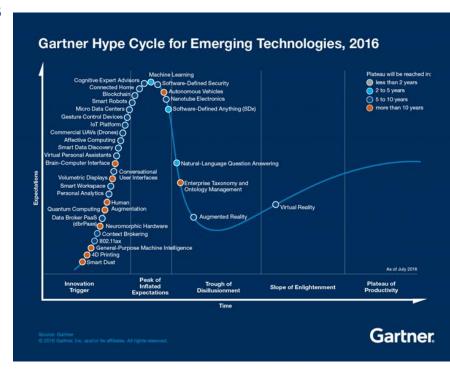
Focus: high-end Gamer (DP and FP16 artificially reduced)

Professional workstation cards and HPC: small niche, ~2 million cards per year (compared to 350 million total GPUs)



Accelerators: GPU (2)

- New focus for graphic cards: machine learning
- Move to FP16 and even INT8 architectures, less precision → 8 bit processing!
- Google TPU Tensor Processing Unit
- New start-ups with special processor designs: e.g. KnuEdge, Nervana (just bought by Intel), krtkl, Eyeriss
- Essentially not usable as general purpose processors (online?!)
- Intel changing strategies also for their KnightsXX processors, 'forking' models (increase FP16 and decrease DP)
 - ~100k units per year, very small market

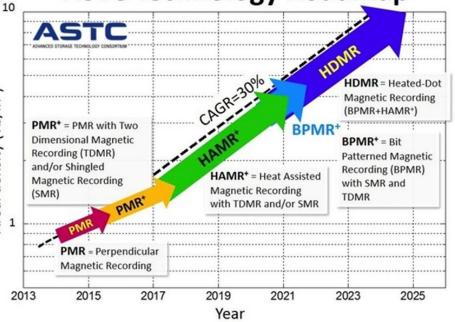


 Qualcomm plans to add neuromorphic chips into the smartphone

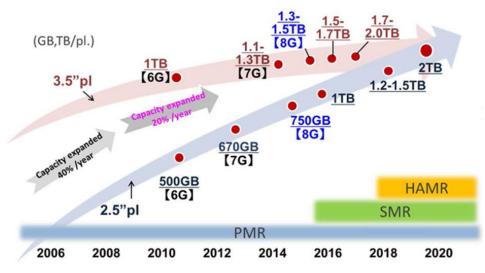


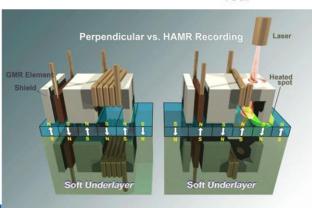
Hard Disks (1)

ASTC Technology Roadmap



[Road map for storage density increase] (SDK forecast)





PMR limit at 1 TbPSI SMR adds ~25%, market small HAMR should provide 5 TbPSI

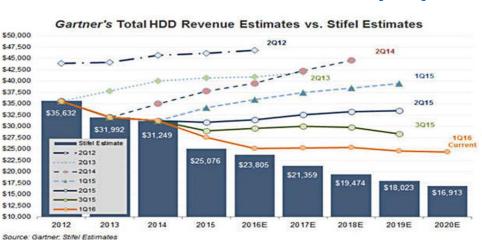
HAMR delayed, production in 2018

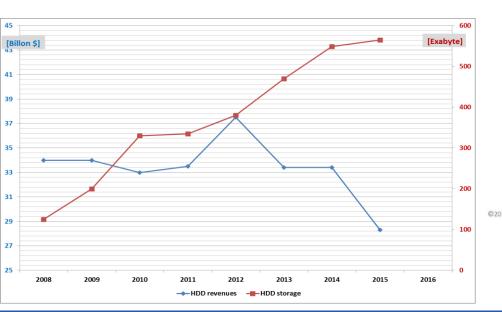
Combining bit density
(30% annual growth rate)
and volume density
(number of platters, helium)
→ 100 TB in 2025
conceivable



Areal density (Tb/in²)

Hard Disks (2)

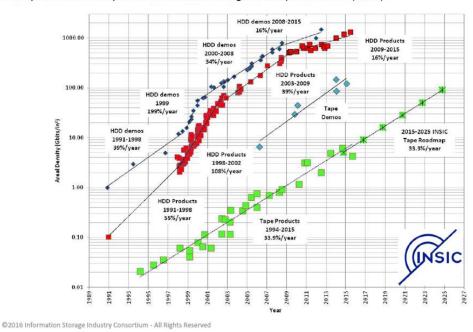




Continuous decrease in revenues Forecast changes every year

Areal Density Trends

Chart provided courtesy of the Information Storage Industry Consortium (INSIC)

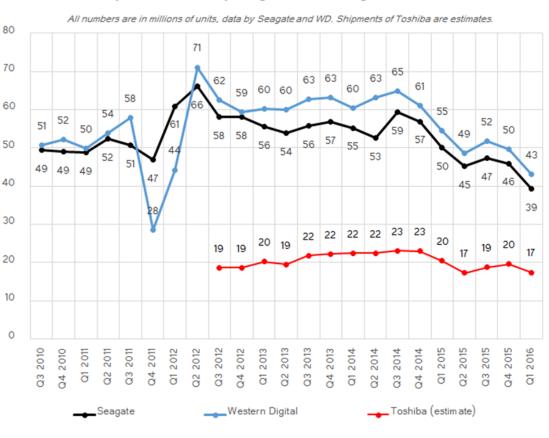


Areal density improvement dropped from ~40% to 16% per year



Hard Disks (3)

Shipments of HDDs by Seagate, Western Digital and Toshiba



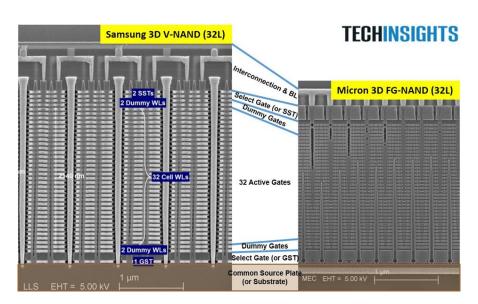
- HDD sales decreasing, related to PC sales decline
- Pressure from SSDs in the notebook area and in the enterprise performance drives (FC, 15krpm)
- Stable sales for capacity cloud drives
- HDD/SSD mergers e.g.
 Western Digital bought SanDisk



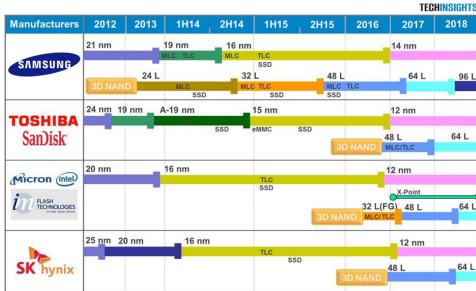
Solid-State Disks (1)

NAND:

- 2D scaling came to an end 2 years ago
- 3D: Samsung 48 layer products in the market; announced 4th generation (64 layers) for next year

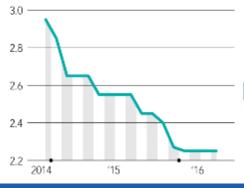


Same name, different technologies and sizes



64-gigabit MLC NAND chip prices

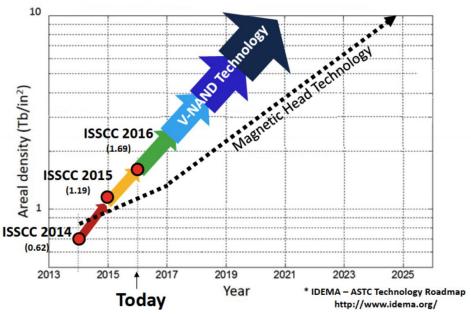
(in dollars per unit)



Expect increasing prices in 2017!

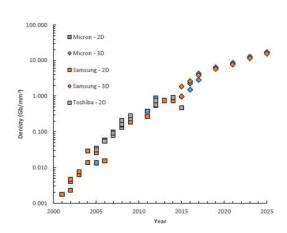


Solid-State Disks (2)

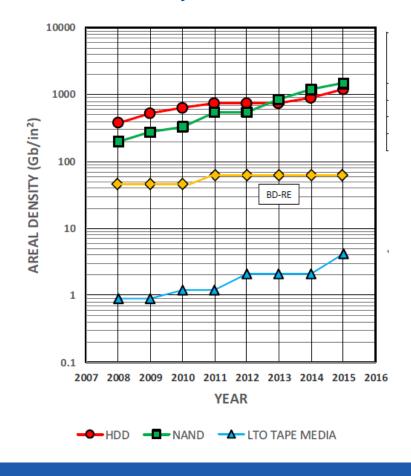


3D NAND – scaling in the third dimension

- 2D NAND scaling beyond 16nm/15nm is uneconomical.
- 3D NAND adds additional layers for scaling in place of 2D lithographic scaling.
- Bit density is continuing to scale with the potential for terabit NAND die.

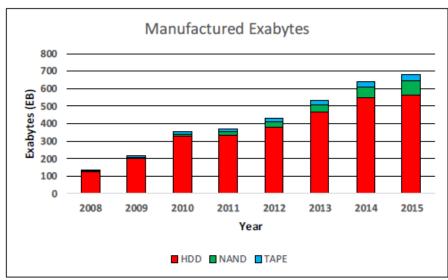


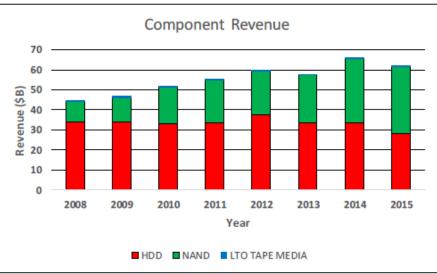
NAND density has surpassed HDD density





Solid-State Disks vs. Hard Disks





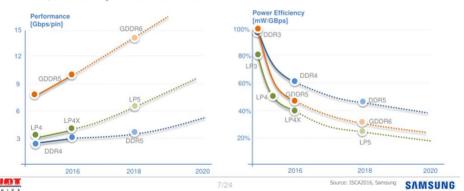
- 14 times more HDD capacity than SSD
- Price per TB decreasing about the same way
- Difference SSD/HDD costs per TB ~5-10 will slowly decrease
- Fab investment of \$100-200 B necessary to achieve HDD ExaByte deliveries
- 4Q2016: supply shortage of NAND, continued in 2017, expect SSD price increases



Memory: DRAM

Memory technology trend

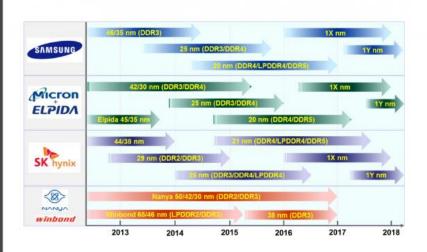
- · GDDR6 with over 14Gbps, beyond 10Gbps GDDR5
- · LP5, 20% more power-efficient than LP4X



DRAM Technology Review

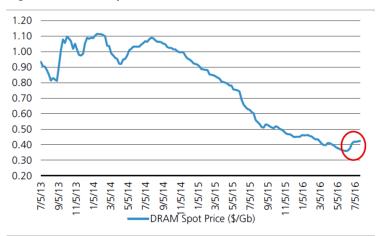
TECHINSIGHTS

■ DRAM Process Node Roadmap (Manufacturers)



Limited future improvements on performance and energy efficiency

Figure 1: DRAM Spot Price Trend



Source: DRAMeXchange

2 Chinese companies will enter the DRAM market in 2017

Short supply started end 2016

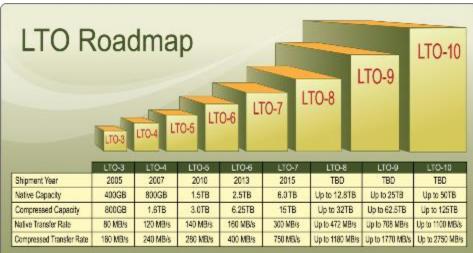
	4Q16	1Q17 (E)
PC DRAM	25%~30%	25%~30%
Server DRAM	10%~15%	20%~25%
Mobile DRAM	3%~7%	10%~15%

New Memory Technologies

- 3d xpoint: new technology from Intel and Micron, presumably a variant of Phase Change Memory
 Specs are changing:
 Announcement 2015: 1000x faster, 1000x endurance, 10x denser than NAND
 IDF 2016: 10x faster, 3x endurance, 4x denser than NAND
 Will enter the high end server market in Q1 2017
- Memristors: developed since 2008; HPE now collaborating with SanDisk (ReRAM)
- Spin torque MRAM in larger production units available (Everquest + Globalfoundries)
 Low density and high price
- Tantalum memory, Rice University
- RRAM or ReRAM, various new categories being developed: Oxide RAM (OxRAM), Conductive-Bridge RAM (CBRAM) or Self-Rectifying Cells (SRC)
- → But... NAND fab investments are high, extended technology lifetime with 3D, hard to replace in the short term



Magnetic Tapes (1)

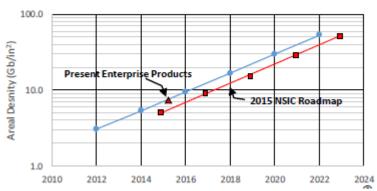


Enterprise drives:

Oracle 2017: 8.5 TB → 12.5 TB IBM 2018: 10 TB → 15-19 TB

- Technology in the lab:
 Fujifilm 154 TB, Sony 185 TB,
 IBM 220 TB
- Good improvements of price/capacity

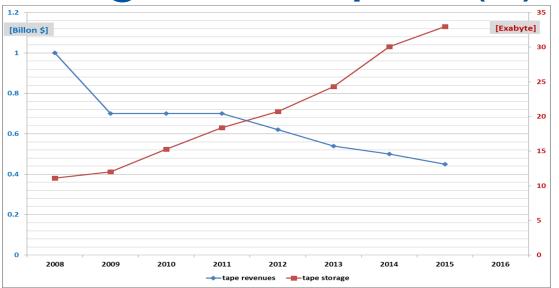
TAPE: source NSIC 2013

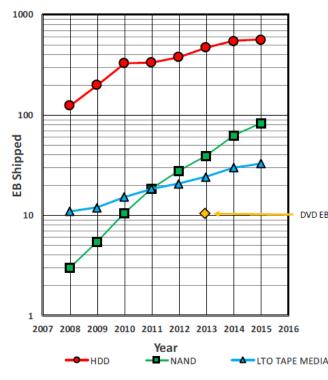






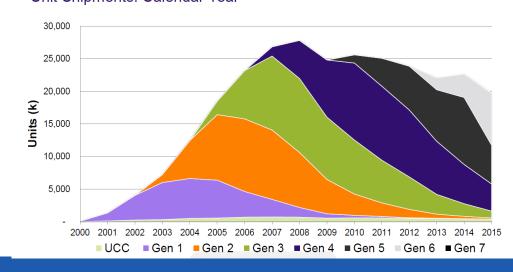
Magnetic Tapes (2)





- More NAND than LTO shipped
- Steady decrease of tapes shipped and revenues
- Will Oracle and/or IBM sell or drop these products?

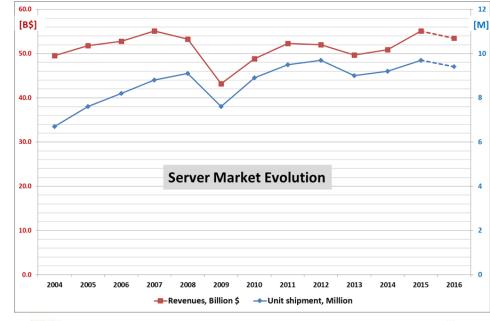
Unit Shipments: Calendar Year

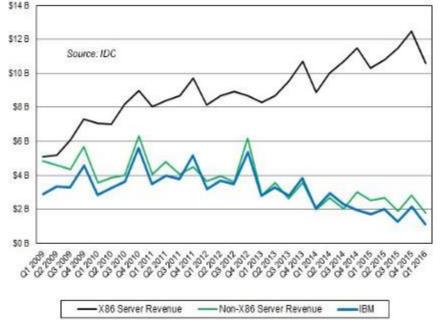




Servers (1)

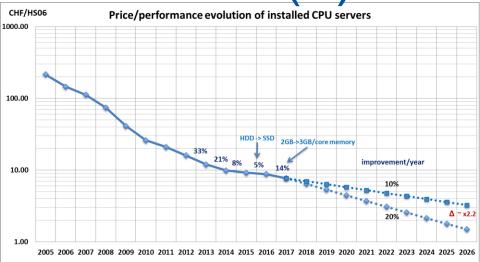
- Server market is saturated: flat revenues and unit shipments
- High profit market
- Single vendor: Intel, 99% market share
- Several initiatives to change that:
- OpenPower (IBM): consortium with many members
 - · But revenues still going down, little impact so far
 - Announcement of POWER9 might help
- ARM server:
 - AppliedMicro, Qualcomm, Cavium: new high end products Announcements for 2H2017 (third ARMv8 Wave 2017-2018), First two waves had little impact
 - Phytium (China), "Mars" processor
- AMD with new processor design (Zen) in 2017
- Fujitsu ARM-powered supercomputer
 - · Add large vector instructions to the ARM design
 - Aimed for 2020, now ~2022







Servers (2)



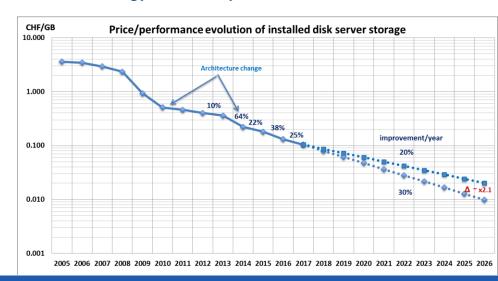
- Moore's Law and Kryder's Law are slowing down
 - 18 months → >= 3 years
- Real cost/performance evolution driven by financial and market aspects rather than technology

Preliminary extrapolation of CPU and disk server costs (based on CERN procurements)

Pessimistic and reasonable improvement extrapolations

Influence of changing software and hardware architecture requirements to be taken into account (programs, data model, data centre, ...)

e.g. CERN moves from 2 to 3 GB/core (+8% cost), driven by experiment usage AND technology boundary conditions





Summary (1)

- Device markets (smartphones, tablets, PCs, notebooks, servers, HPC) saturated or even negative growth
 - Replacement market
- Moore's Law in trouble, financial issues
 - Not clear how this effects price/performance evolution
 - So far okay for CPU and disk servers
- Technology improvements still continuing, but requires high CAPEX
 End-product price tag evolution more complicated
- Market dominance of few companies increases, competition diminishing



Summary (2)

- Technology unlikely to solve the HL-LHC computing problem
 - Not much more to be expected than minor contributions



References

http://electroiq.com/blog/2016/05/global-semiconductor-sales-increase-slightly-in-march/

http://www.statista.com/statistics/266219/global-smartphone-sales-since-1st-quarter-2009-by-operating-system/

http://www.statista.com/statistics/263393/global-pc-shipments-since-1st-quarter-2009-by-vendor/

http://www.statista.com/statistics/276651/global-media-tablet-shipments-since-3rd-quarter-2011-by-vendor/

https://www.ericsson.com/res/docs/2016/ericsson-mobility-report-2016.pdf

http://www.nasdaq.com/article/the-evolution-of-smartphone-markets-where-growth-is-going-cm619105

http://www.potomacinstitute.org/steps/images/PDF/Articles/FritzeSTEPS_2016lssue3.pdf

http://www.pcper.com/news/Processors/Intel-officially-ends-era-tick-tock-processor-production

http://semimd.com/chipworks/

http://www.extremetech.com/extreme/223022-the-myths-of-moores-law

http://www.forbes.com/sites/gartnergroup/2016/08/29/track-three-trends-in-the-2016-gartner-hype-cycle-for-emerging-technologies/#59fc4d787286

http://jonpeddie.com/publications/market_watch

http://www.anandtech.com/show/10613/discrete-desktop-gpu-market-trends-q2-2016-amd-grabs-market-share-but-nvidia-remains-on-top

http://www.computerworld.com/article/3041947/data-storage/how-these-technologies-will-blow-the-lid-off-data-storage.html

http://www.computerworld.com/article/2852233/want-a-100tb-disk-drive-youll-have-to-wait-til-2025.html

http://www.anandtech.com/show/9866/hard-disk-drives-with-hamr-technology-set-to-arrive-in-2018

http://www.theregister.co.uk/2016/05/31/hdd_revenues_to_plummet_as_ssd_penetration_rises/

http://www.anandtech.com/show/10315/market-views-hdd-shipments-down-q1-2016

http://www.trendfocus.com/ssd-cq116_update/

http://www.forbes.com/sites/tomcoughlin/2016/02/03/flash-memory-areal-densities-exceed-those-of-hard-drives/#5dc24d2b4026

http://www.anandtech.com/show/10589/hot-chips-2016-memory-vendors-discuss-ideas-for-future-memory-tech-ddr5-cheap-hbm-more

http://asia.nikkei.com/Business/Trends/NAND-flash-memory-prices-likely-to-climb-again

http://www.techinsights.com/techinsights/about-techinsights/articles/deep-dive-into-the-intel-micron-3D-32L-FG-NAND/

http://amigobulls.com/articles/micron-technology-inc-stock-is-the-next-big-idea-for-2016

http://wccftech.com/micron-compete-samsung-16-nm-dram/

http://storageconference.us/2016/Slides/BobFontana.pdf

http://searchsolidstatestorage.techtarget.com/feature/New-memory-technologies-generate-attention-as-successors-to-NAND-flash

http://www.itjungle.com/tfh/tfh061316-story05.html

http://www.forbes.com/sites/tomcoughlin/2016/01/15/digital-storage-projections-for-2016-part-2/2/#35b1916a3aa8

http://www.lto.org/wp-content/uploads/2016/03/LTO_Media-Shipment-Report_3.22.16.pdf

http://semiaccurate.com/2016/09/12/intels-xpoint-pretty-much-broken/





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